

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	294	cmp with roughness	USPAT; US-PGPUB	2003/05/27 09:50

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1	BRS	170	("3" adj (d or dimentional)) with (ic or (integrtd adj circuit))	USPAT; US-PGPUB	2003/05/23 13:32

	Document ID	Pages	Title	Current OR	Current XRef	Inventor
1	US 20030068871 A1	11	Three dimensional integrated circuits	438/486	257/52; 257/64; 438/482; 438/795	Chan, Man Sun John et al.
2	US 5424920 A	12	Non-conductive end layer for integrated stack of IC chips	361/735	257/686; 257/704; 257/777; 257/E23.011; 257/E25.013; 361/744; 361/792	Miyake, Michael K.
3	US 5818748 A	24	Chip function separation onto separate stacked chips	365/51	257/686; 257/777; 257/E25.013; 365/63; 365/72	Bertin, Claude Louis et al.
4	US 6355976 B1	27	Three-dimensional packaging technology for multi-layered integrated circuits	257/686	257/685; 257/723; 257/724; 257/E23.103; 257/E23.177; 257/E25.011	Faris, Sadeg M.